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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:	)	Group Art Unit: 2812
KUWAZAWA	)	
Serial No. 09 885,761	)	Examiner: Isaac, Stanetta D.
Filed: June 19, 2001	)	
For: METHODS FOR MANUFACTURING	)	
SEMICONDUCTOR DEVICES AND	)	
SEMICONDUCTOR DEVICES	)	

## **AMENDMENT**

Assistant Commissioner for Patents Washington, D.C. 20231

Dear Sirs:

In response to the Office Action dated May 20, 2002, please enter and consider the following:

## IN THE DRAWINGS:

In Figs. 5-6, applicant proposes to insert the terms -- Prior Art--.

## IN THE CLAIMS:

RECEIVED

Please cancel claims 10-20 without prejudice.

DEC V 3 2902

UFFICE OF PETITIONS

Please amend claims 1-3 and 21-24 as follows:

- 1. (amended) A method for manufacturing a semiconductor device, the method comprising:
  - (a) forming a gate dielectric layer over a semiconductor substrate;
  - (b) forming a gate electrode over the gate dielectric layer;
  - (c) forming a dielectric layer over the semiconductor substrate;
  - (d) forming a mask layer over the dielectric layer;
- (e) anisotropically etching the mask layer to form a sidewall mask layer on sides of the gate electrode over the dielectric layer;